#### **ABSOLUTE MAXIMUM RATINGS**

(Voltages Referenced to GND)

V+	0.3V to +6V
All Other Pins (Note 1)	0.3V to (V+ + 0.3V)
Continuous Current COM, NO	±20mA
Peak Current COM, NO_	
(pulsed at 1ms, 10% duty cycle)	±40mA
ESD per Method 3015.7	>2kV

Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )
10-Pin µMAX (derate 4.7mW/°C above +70°C) 330mW
12-Pin QFN (derate 11.9mW/°C above +70°C) 952mW
Operating Temperature Range40°C to +85°C
Storage Temperature Range65°C to +150°C
Lead Temperature (soldering, 10s) +300°C

Note 1: Signals on INH, ADD\_, NO\_, and COM exceeding V+ or GND are clamped by internal diodes. Limit forward-diode current to maximum current rating.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### ELECTRICAL CHARACTERISTICS—Single +3V Supply

 $(V + = +2.7V \text{ to } +3.3V, V_{IH} = +1.4V, V_{IL} = +0.5V, T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise noted}.$  Typical values are at V + = +3V and  $T_A = +25^{\circ}\text{C}.$ ) (Notes 2, 3)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	ТҮР	MAX	UNITS
ANALOG SWITCH			·				
Analog Signal Range	V <sub>COM</sub> , V <sub>NO</sub>			0		V+	V
On-Resistance	Davi	V+ = +2.7V, I <sub>COM</sub> = 5mA,	+25°C		50	60	0
	R <sub>ON</sub>	$V_{NO_{-}} = +1.3V$	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			70	Ω
On-Resistance Match	ΔRon	$V + = +2.7V$ , $I_{COM} = 5mA$ ,	+25°C		1	3	Ω
Between Channels (Note 4)	ANON	$V_{NO_{-}} = +1.3V$	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			5	52
On-Resistance Flatness	RFLAT (ON)	$V + = +2.7V$ , $I_{COM} = 5mA$ ,	+25°C		3	5	5 Ω
(Note 5)	TFLAT (ON)	V <sub>NO</sub> = +1V, +1.3V, +1.8V	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			10	52
NO_ Off-Leakage	I <sub>NO</sub> (OFF)	$V + = +3.3V, V_{COM} = +0.3V, +3V$	+25°C	-0.1	±0.01	0.1	0.1 1 nA
Current (Note 6)	INO_(OFF)	$V_{NO_{-}} = +3V, +0.3V$	T <sub>MIN</sub> to T <sub>MAX</sub>	-1		1	
COM On-Leakage Current (Note 6)	ICOM(ON)	$V{+} = +3.3V, V_{COM} = +0.3V, +3V \\ V_{NO_{-}} = +0.3V, +3V, \text{ or floating}$	+25°C	-0.5	±0.01	0.5	- nA
			$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$	-5		5	
COM Off-Leakage Current	1	kage Current $V_{+} = +3.3V, V_{COM} = +0.3V, +3V +25^{\circ}C$	+25°C	-0.5	±0.01	0.5	nA
(Note 6)	ICOM(OFF)	$V_{NO_{-}} = +3V, +0.3V$	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$	-5		5	
DYNAMIC							
Address Transition Time	t== 1.1.0	$V_{NO_{}} = +1.5V, R_{L} = 300\Omega,$	+25°C		20	60	20
Address transition time	<b>t</b> TRANS	$C_L = 35 pF$ , Figure 2	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			70	ns
Inhibit Turn-On Time		$V_{NO_{-}} = +1.5V, R_{L} = 300\Omega,$ $C_{L} = 35pF, Figure 3$	+25°C		25	60	
Innibit Tum-On Time	ton		T <sub>MIN</sub> to T <sub>MAX</sub>			70	ns
Inhibit Turn-Off Time	<b>1</b> .	$V_{NO_{-}} = +1.5V, R_{L} = 300\Omega,$	+25°C		10	20	<b>D0</b>
innibit turn-Ott time	tOFF	$C_L = 35pF$ , Figure 3	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			30	ns
Break-Before-Make Time	$V_{NO_{-}} = +1.5V, R_{L} = 300\Omega,$	+25°C		20		<b>D0</b>	
(Note 7)	rBBM	$t_{\text{BBM}}$ C <sub>L</sub> = 35pF, Figure 4		2			ns
Charge Injection	Q	$V_{GEN} = 0$ , $R_{GEN} = 0$ , $C_L = 1.0$ nF, Figure 5			2		рС

#### ELECTRICAL CHARACTERISTICS—Single +3V Supply (continued)

 $(V + = +2.7V \text{ to } +3.3V, V_{IH} = +1.4V, V_{IL} = +0.5V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ , unless otherwise noted. Typical values are at V + = +3V and  $T_A = +25^{\circ}C$ .) (Notes 2, 3)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	ТҮР	MAX	UNITS
On-Channel -3dB Bandwidth	BW	Signal = 0dBm, 50 $\Omega$ in and out, Figure 6			>200		MHz
Off-Isolation (Note 8)	V <sub>ISO</sub>	f = 1MHz, R <sub>L</sub> = 50 $\Omega$ , C <sub>L</sub> = 5pF, Figure 6			-85		dB
Crosstalk (Note 9)	V <sub>CT</sub>	f = 1MHz, R <sub>L</sub> = 50 $\Omega$ , C <sub>L</sub> = 5pF, Figure 6			-90		dB
NO_ Off-Capacitance	C <sub>NO_(OFF)</sub>	f = 1MHz, V <sub>NO</sub> = GND, Figure 7			7		pF
COM On-Capacitance	CCOM(ON)	f = 1MHz, V <sub>NO</sub> = GND, Figure 7			19		pF
COM Off-Capacitance	CCOM(OFF)	$f = 1MHz, V_{NO_{-}} = GND, Figure 7$			15		pF
DIGITAL I/O							
Input Logic High	VIH			1.4			V
Input Logic Low	VIL					0.5	V
Input Leakage Current	l <sub>IH</sub> , l <sub>IL</sub>	ADD_, INH = 0 or V+		-1		1	μA
SUPPLY							
Power-Supply Range	V+			1.8		5.5	V
Power-Supply Current	+	V+ = +5.5V, ADD_, INH = 0 or V+				1	μA

#### ELECTRICAL CHARACTERISTICS—Single +5V Supply

(V+ = +4.5V to +5.5V, V<sub>IH</sub> = +2.0V, V<sub>IL</sub> = +0.8V, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted. Typical values are at V+ = +5V and T<sub>A</sub> = +25°C.) (Notes 2, 3)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	ТҮР	MAX	UNITS	
ANALOG SWITCH								
Analog Signal Range	VCOM, VNO_			0		V+	V	
On-Resistance	Davi	V+ = +4.5V, I <sub>COM</sub> = 5mA,	+25°C		30	40	Ω	
	Ron	$V_{NO_{-}} = +3.5V$	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			50		
On-Resistance Match	APou	V+ = +4.5V, I <sub>COM</sub> = 5mA,	+25°C		1	2	Ω	
Between Channels (Note 4)	$\Delta R_{ON}$	$V_{NO} = +3.5V$	T <sub>MIN</sub> to T <sub>MAX</sub>			3	52	
On-Resistance Flatness	Det te (a)	V+ = +4.5V, I <sub>COM</sub> = 5mA,	+25°C		3	5	Ω	
(Note 5)	RFLAT (ON)	<sup>)</sup> V <sub>NO</sub> = +1V, +2.25V, +3.5V	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			10	52	
NO_Off-Leakage		V+ = +5.5V, V <sub>COM</sub> = +0.5V, +5V	+25°C	-0.1	±0.01	0.1		
Current (Note 6)	INO_(OFF)	$V_{NO_{-}} = +5V, +0.5V$	T <sub>MIN</sub> to T <sub>MAX</sub>	-1		1	1 nA	
COM On-Leakage Current		V+ = +5.5V, V <sub>COM</sub> = +0.5V, +5V	+25°C	-0.5	±0.01	0.5	0.5	
(Note 6)	$V_{NO}$ = +0.5V, +5V, or floating	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$	-5		5	nA		

#### ELECTRICAL CHARACTERISTICS—Single +5V Supply (continued)

(V+ = +4.5V to +5.5V, V<sub>IH</sub> = +2.0V, V<sub>IL</sub> = +0.8V, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted. Typical values are at V+ = +5V and T<sub>A</sub> = +25°C.) (Notes 2, 3)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS
COM Off-Leakage Current		V+ = +5.5V, V <sub>COM</sub> = +0.5V, +5V	+25°C	-0.5	±0.01	0.5	nA
COM ON-Leakage Current	ICOM(OFF)	$V_{NO_{}} = +5V, +0.5V$	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$	-5		5	ΠA
DYNAMIC							
Address Transition Time	TRANO	$V_{NO_{-}} = +3V, R_{L} = 300\Omega,$	+25°C		15	35	nc
Address transition time	<b>t</b> TRANS	C <sub>L</sub> = 35pF, Figure 2	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			40	ns
Inhibit Turn-On Time	ton	$V_{NO_{-}} = +3V, R_{L} = 300\Omega,$	+25°C		18	35	ns
	UN	C <sub>L</sub> = 35pF, Figure 3	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			40	115
Inhibit Turn-Off Time	tOFF	$V_{NO_{-}} = +3V, R_{L} = 300\Omega,$	+25°C		9	20	20 30 ns
	UFF	C <sub>L</sub> = 35pF, Figure 3	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$			30	
Break-Before-Make Time	tBBM	$V_{NO_{-}} = +3V, R_{L} = 300\Omega,$	+25°C		20		ns
(Note 7)	UDIVI	$C_L = 35 pF$ , Figure 4	$T_{\mbox{MIN}}$ to $T_{\mbox{MAX}}$	2			113
Charge Injection	Q	$V_{GEN} = 0$ , $R_{GEN} = 0$ , $C_L = 1.0nF$ , Figure 5			3		рС
On-Channel -3dB Bandwidth	BW	Signal = 0dBm, 50 $\Omega$ in and out, Figure 6			>200		MHz
Off-Isolation (Note 8)	VISO	f = 1MHz, $R_L$ = 50 $\Omega$ , $C_L$ = 5pF, Figure 6			-85		dB
Crosstalk (Note 9)	V <sub>CT</sub>	f = 1MHz, R <sub>L</sub> = 50 $\Omega$ , C <sub>L</sub> = 5pF, Figure 6			-90		dB
Total Harmonic Distortion	THD	f = 20Hz to 20kHz, 1Vp-p, R <sub>L</sub> = $600\Omega$			0.02		%
DIGITAL I/O							
Input Logic High	VIH			2.0			V
Input Logic Low	VIL					0.8	V
Input Leakage Current	I <sub>IH</sub> , I <sub>IL</sub>	ADD_, $INH = 0 \text{ or } V+$		-1		1	μA
SUPPLY							
Power-Supply Range	V+			1.8		5.5	V
Positive Supply Current	l+	V+ = +5.5V, ADD_, INH = 0 or V+				1	μA

Note 2: The algebraic convention, where the most negative value is a minimum and the most positive value a maximum, is used in this data sheet.

**Note 3:** -40°C specifications are guaranteed by design.

**Note 4:**  $\Delta R_{ON} = R_{ON}(MAX) - R_{ON}(MIN)$ .

Note 5: Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal ranges.

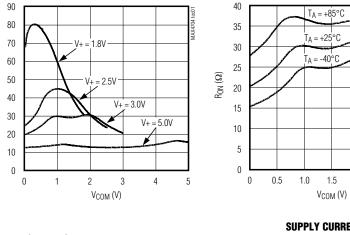
**Note 6:** Leakage currents are 100% tested at  $T_A = +85^{\circ}$ C. Limits across the full temperature range are guaranteed by correlation. **Note 7:** Guaranteed by design.

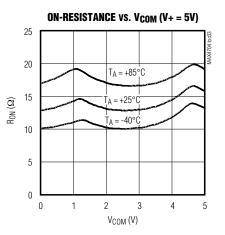
**Note 8:** Off-Isolation =  $20\log_{10} (V_{COM} / V_{NO}), V_{COM} = output, V_{NO} = input to off switch.$ 

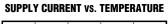
Note 9: Between any two switches.

**MAX4704** 

#### **Typical Operating Characteristics**



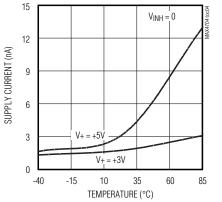




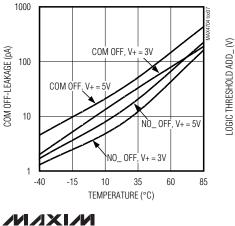
 $(T_A = +25^{\circ}C, unless otherwise noted.)$ 

 $R_{ON}(\Omega)$ 

**ON-RESISTANCE VS. VCOM** 







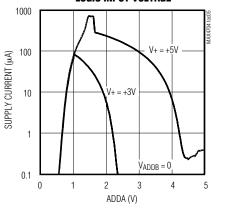


2.0

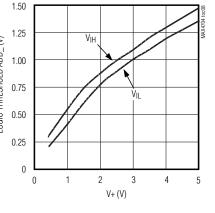
2.5

3.0

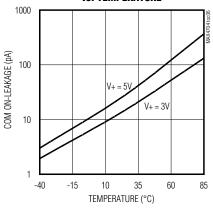
ON-RESISTANCE vs. V<sub>COM</sub> (V+ = 3V)



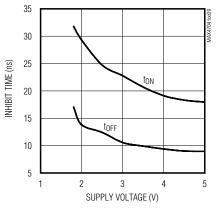


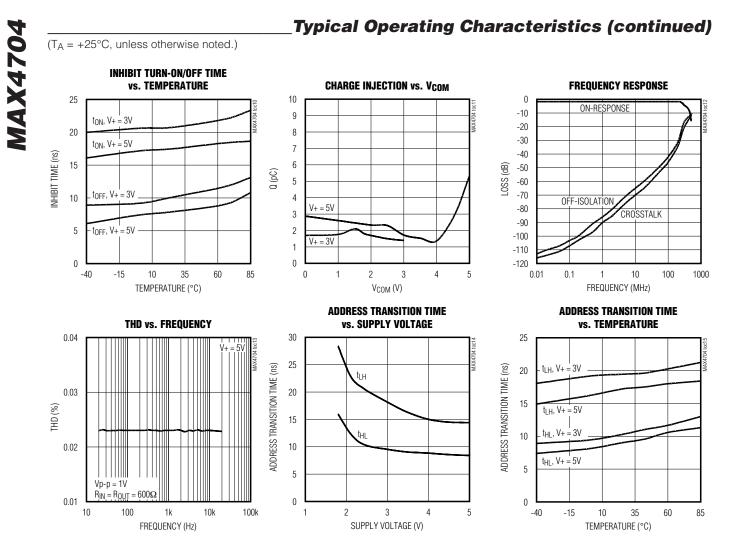


COM ON-LEAKAGE CURRENT vs. TEMPERATURE



INHIBIT TURN-ON/OFF TIME vs. supply voltage





**Pin Description** 

P	PIN NAME		PIN		FUNCTION
μΜΑΧ			FUNCTION		
10	1	V+	Positive Supply Voltage		
_	2, 8	N.C.	No Connection. Not internally connected.		
1	3	NO2	Analog Switch 2. Normally open.		
2	4	NO3	Analog Switch 3. Normally open.		
3	5	NO1	Analog Switch 1. Normally open.		
4	6	INH	Inhibit. Connect to GND for normal operation. Connect to logic-level high to turn all switches off.		
5	7	GND	Ground		
6	9	ADDB	Address Decoder Selection B		
7	10	ADDA	Address Decoder Selection A		
8	11	NO0	Analog Switch 0. Normally open.		
9	12	COM	Analog Switch Common Terminal		
	_	EP	Exposed Pad. Internally connected to GND. Connect to a large ground plane to maximize thermal performance; not intended as an electrical connection point (QFN package only).		

#### **Detailed Description**

The MAX4704 low-voltage, 4-channel analog multiplexer operates from a single +1.8V to +5.5V supply. When powered from a +2.7V supply, the device has a 60 $\Omega$  (max) on-resistance (R<sub>ON</sub>), with 3 $\Omega$  (max) R<sub>ON</sub> matching and 5 $\Omega$  (max) R<sub>ON</sub> flatness. The digital logic inputs are +1.8V-logic compatible from a +2.7V to +3.3V supply.

#### **Applications Information**

#### **Digital Control Inputs**

The MAX4704 logic inputs are +1.8V CMOS logic compatible for 3V operation and TTL compatible for 5V operation of V+. Driving ADD\_ rail-to-rail minimizes power consumption.

#### **Analog Signal Levels**

Analog signals that range over the entire supply voltage (V+ to GND) are passed with very little change in on-resistance (see *Typical Operating Characteristics*). The switches are bidirectional, so the NO\_ and COM pins can be either inputs or outputs.

#### Power-Supply Sequencing and Overvoltage Protection

Caution: Do not exceed the absolute maximum ratings because stresses beyond those listed may cause permanent damage to devices.

Proper power-supply sequencing is recommended for all CMOS devices. Always apply V+ before applying analog signals, especially if the analog signal is not current limited. If this sequencing is not possible, and if the analog inputs are not current limited to <20mA, add a small-signal diode

(D1) as shown in Figure 1. If the analog signal can dip below GND, add D2. Adding protection diodes reduces the analog range to a diode drop (about 0.7V) below V+ (for D1), and a diode drop above ground (for D2). On-resistance increases slightly at low supply voltages. Maximum supply voltage (V+) must not exceed +6V.

Adding protection diode D2 causes the logic threshold to be shifted relative to GND. TTL compatibility is not guaranteed when D2 is added.

Protection diodes D1 and D2 also protect against some overvoltage situations. In the circuit in Figure 1, if the supply voltage is below the absolute maximum rating, and if a fault voltage up to the absolute maximum rating is applied to an analog signal pin, no damage will result.

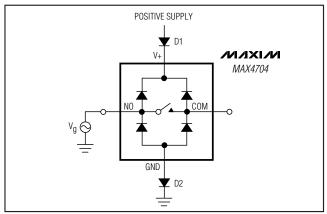


Figure 1. Overvoltage Protection Using Two External Blocking Diodes



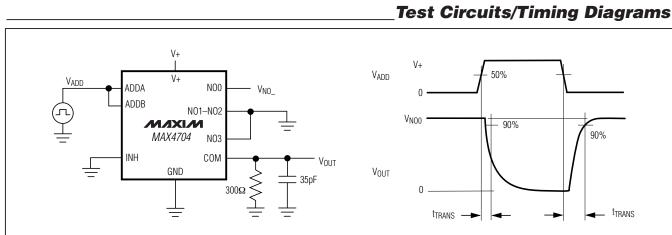


Figure 2. Address Transition Time

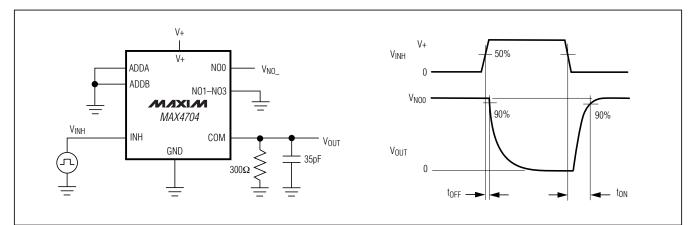
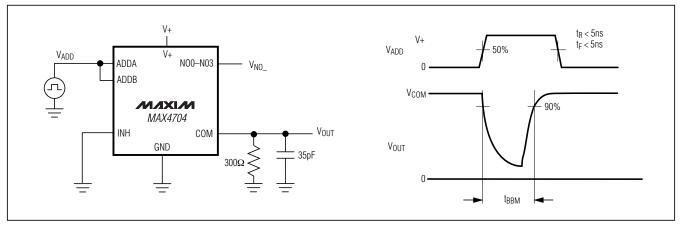


Figure 3. Inhibit Switching Times



MXXVN

Figure 4. Break-Before-Make Interval

#### \_Test Circuits/Timing Diagrams (continued)

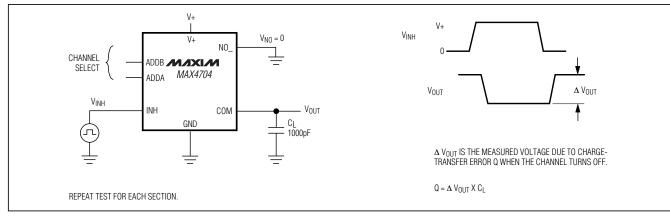


Figure 5. Charge Injection

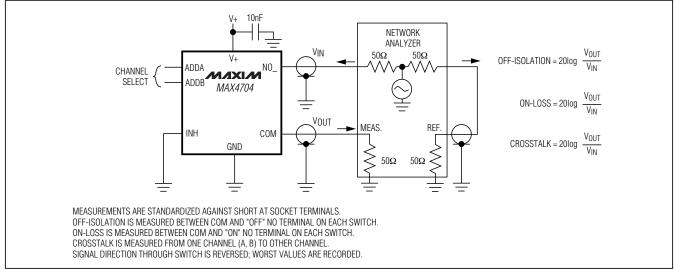


Figure 6. Off-Isolation, On-Loss, and Crosstalk

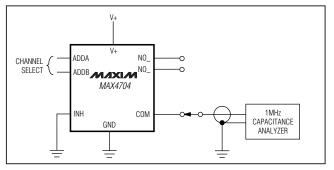


Figure 7. NO\_/COM Capacitance



#### **Chip Information**

TRANSISTOR COUNT: 256 PROCESS: CMOS

9

**MAX4704** 

**Package Information** 

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
12 QFN-EP	G1233-1	<u>21-0102</u>
10 µMAX		<u>21-0061</u>

#### **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	10/01	Initial release	—
1	10/08	Inserted exposed paddle description	1, 7

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